

TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

JBT6K49-AS

Power supply IC for TFT LCD Panels

The JBT6K49-AS chip is an integrated circuit (IC) for generating the supply voltages necessary for a TFT LCD panel driver. When used in combination with the T6K47 source driver and the T6K48 gate driver for TFT LCD panels, the JBT6K49-AS enables the module set to operate with low power consumption.

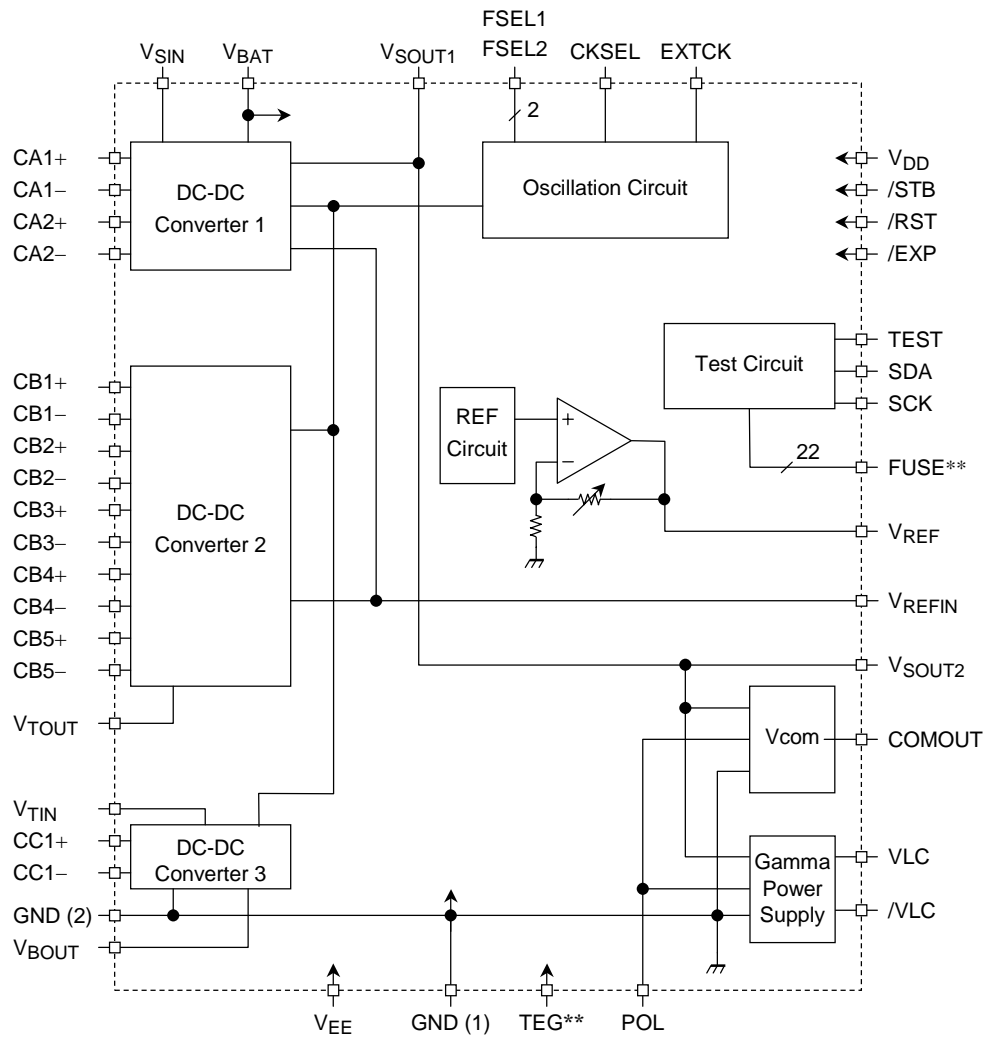
A high-speed CMOS process is employed to achieve low power consumption and high-speed operation for the JBT6K49-AS.

Features

- Built-in circuits : DC-DC converters and oscillation circuit for DC-DC converters
High-precision regulator
Binary buffer for γ -correction
Level shifter circuit for V_{com}
- Supply voltage (V_{DD}) : 2.7 V to 3.3 V
- Supply voltage (V_{BAT}) : 2.7 V to 4.2 V
- Low power consumption
- Operating temperature : -20°C to 75°C
- CMOS process
- Recommended drivers : T6K47 source driver for TFT LCD
T6K48 gate driver for TFT LCD
- Package :

Product Name	Description
JBT6K49-AS (PI)	Gold bump chip

Block Diagram



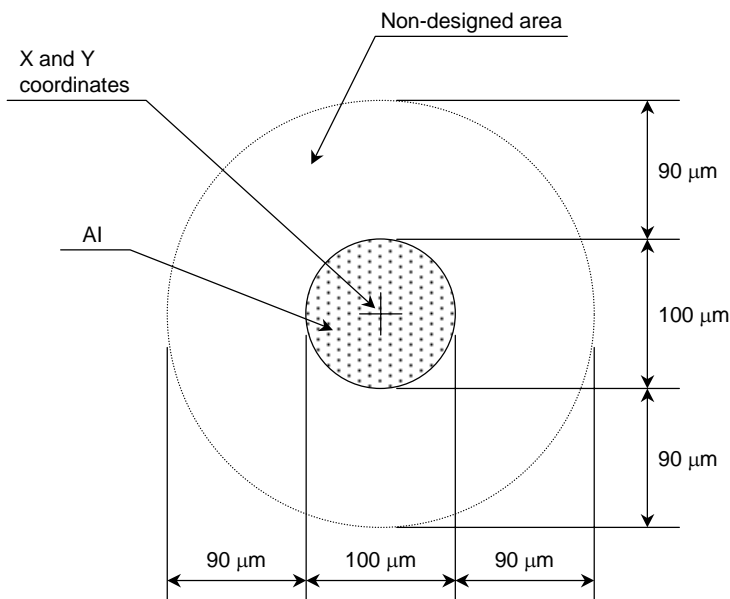
PAD Specifications

Characteristics		Size	Unit
Chip Size		4600 × 3050	μm
Chip End Coordinates	(1)	-2300, 1525	μm
	(2)	-2300, -1525	
	(3)	2300, -1525	
	(4)	2300, 1525	
Bump Pitch		140	μm
Bump Height		15	μm

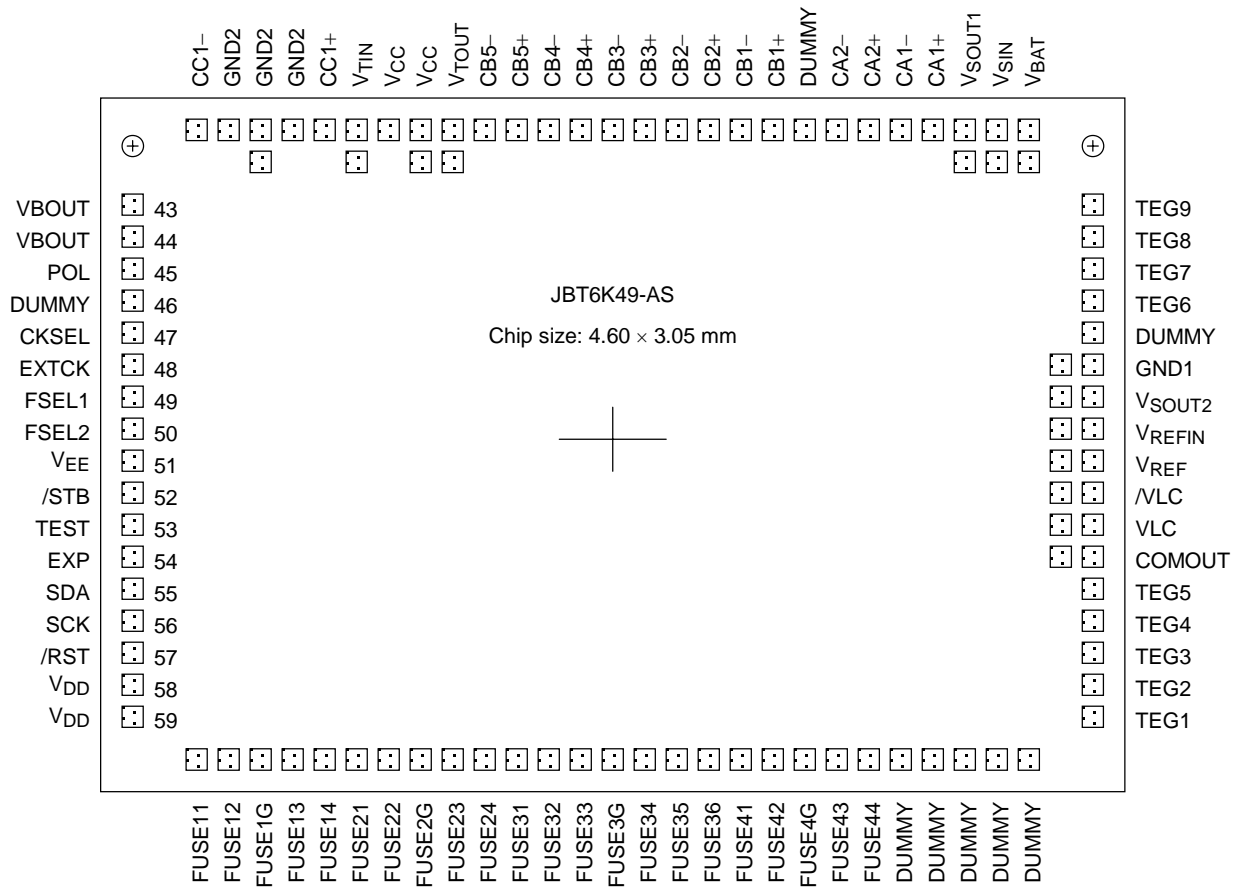
Characteristics	Number of Pins
TEG pin	9
FUSE pin	22

Note 1: The TEG1 to TEG9 pins and the FUSE** pins are reserved for testing by Toshiba. They are not intended to be used in the operation of the JBT6K49-AS. They must always be left open during normal operation.

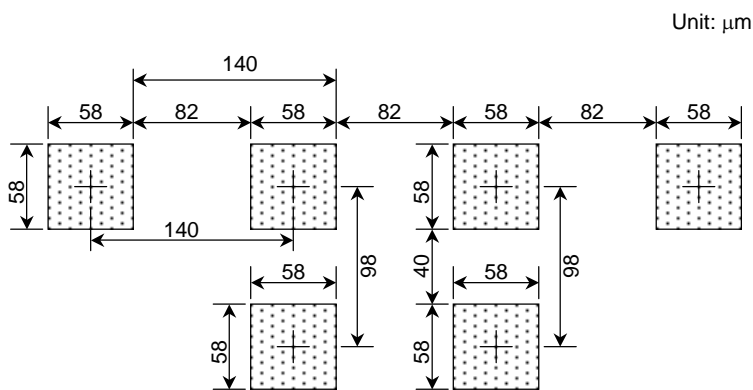
Alignment Mark Specifications



PAD Layout



Input/Output Pins



Pad Coordinates

[Unit: μm]

No.	Pin Name	X-Coordinate	Y-Coordinate	No.	Pin Name	X-Coordinate	Y-Coordinate	No.	Pin Name	X-Coordinate	Y-Coordinate
1	FUSE11	-1890	-1340	44	VSOUT2	2015	160	87	VBOUT	-2115	860
2	FUSE12	-1750	-1340	45	GND1	2115	300	88	POL	-2115	720
3	FUSE1G	-1610	-1340	46	GND1	2015	300	89	DUMMY	-2115	580
4	FUSE13	-1470	-1340	47	DUMMY	2115	440	90	CKSEL	-2115	440
5	FUSE14	-1330	-1340	48	TEG6	2115	580	91	EXTCK	-2115	300
6	FUSE21	-1190	-1340	49	TEG7	2115	720	92	FSEL1	-2115	160
7	FUSE22	-1050	-1340	50	TEG8	2115	860	93	FSEL2	-2115	20
8	FUSE2G	-910	-1340	51	TEG9	2115	1000	94	V _{EE}	-2115	-120
9	FUSE23	-770	-1340	52	VBAT	1750	1340	95	/STB	-2115	-260
10	FUSE24	-630	-1340	53	VBAT	1750	1240	96	TEST	-2115	-400
11	FUSE31	-490	-1340	54	VSIN	1610	1340	97	EXP	-2115	-540
12	FUSE32	-350	-1340	55	VSIN	1610	1240	98	SDA	-2115	-680
13	FUSE33	-210	-1340	56	VSOUT1	1470	1340	99	SCK	-2115	-820
14	FUSE3G	-70	-1340	57	VSOUT1	1470	1240	100	/RST	-2115	-960
15	FUSE34	70	-1340	58	CA1+	1330	1340	101	V _{DD}	-2115	-1100
16	FUSE35	210	-1340	59	CA1-	1190	1340	102	V _{DD}	-2115	-1240
17	FUSE36	350	-1340	60	CA2+	1050	1340	103	A/M_1	2110	1335
18	FUSE41	490	-1340	61	CA2-	910	1340	104	A/M_2	-2110	1335
19	FUSE42	630	-1340	62	DUMMY	770	1340				
20	FUSE4G	770	-1340	63	CB1+	630	1340				
21	FUSE43	910	-1340	64	CB1-	490	1340				
22	FUSE44	1050	-1340	65	CB2+	350	1340				
23	DUMMY	1190	-1340	66	CB2-	210	1340				
24	DUMMY	1330	-1340	67	CB3+	70	1340				
25	DUMMY	1470	-1340	68	CB3-	-70	1340				
26	DUMMY	1610	-1340	69	CB4+	-210	1340				
27	DUMMY	1750	-1340	70	CB4-	-350	1340				
28	TEG1	2115	-1240	71	CB5+	-490	1340				
29	TEG2	2115	-1100	72	CB5-	-630	1340				
30	TEG3	2115	-960	73	VTOUT	-770	1340				
31	TEG4	2115	-820	74	VTOUT	-770	1240				
32	TEG5	2115	-680	75	V _{CC}	-910	1340				
33	COMOUT	2115	-540	76	V _{CC}	-910	1240				
34	COMOUT	2015	-540	77	V _{CC}	-1050	1340				
35	VLC	2115	-400	78	V _{TIN}	-1190	1340				
36	VLC	2015	-400	79	V _{TIN}	-1190	1240				
37	/VLC	2115	-260	80	CC1+	-1330	1340				
38	/VLC	2015	-260	81	GND2	-1470	1340				
39	V _{REF}	2115	-120	82	GND2	-1610	1340				
40	V _{REF}	2015	-120	83	GND2	-1610	1240				
41	V _{REFIN}	2115	20	84	GND2	-1750	1340				
42	V _{REFIN}	2015	20	85	CC1-	-1890	1340				
43	VSOUT2	2115	160	86	VBOUT	-2115	1000				

Pin Function Description (1)

Pin Name	I/O	Function															
CKSEL	I	External clock pulse selection pin CKSEL = "L" . . . the built-in oscillator is used. CKSEL = "H" . . . an external clock pulse is accepted. It must be input on the EXTCK pin.															
EXTCK	I/O	External clock pulse input pin Input an external clock pulse on this pin if External Clock Pulse Supply Mode has been selected. If the built-in oscillator is selected (Self-Oscillation Mode), this pin must be fixed Low.															
FSEL1 FSEL2	I	Oscillation frequency switching input pins These pins can be used to select the oscillation frequency for the DC-DC converters. <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>FSEL2</th> <th>FSEL1</th> <th>DC-DC converter clock frequency (typ.)</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>3.5 kHz</td> </tr> <tr> <td>0</td> <td>1</td> <td>5.0 kHz</td> </tr> <tr> <td>1</td> <td>0</td> <td>7.5 kHz</td> </tr> <tr> <td>1</td> <td>1</td> <td>10.0 kHz</td> </tr> </tbody> </table>	FSEL2	FSEL1	DC-DC converter clock frequency (typ.)	0	0	3.5 kHz	0	1	5.0 kHz	1	0	7.5 kHz	1	1	10.0 kHz
FSEL2	FSEL1	DC-DC converter clock frequency (typ.)															
0	0	3.5 kHz															
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1	1	10.0 kHz															
CA1+, CA1- CA2+, CA2-	I/O	DC-DC converter 1 capacitor connection pins These pins can be connected to voltage booster capacitors. The recommended capacitance for the DC-DC converter capacitors is 1 μ F.															
V _S OUT1 V _S OUT2	O	DC-DC converter 1 output pins These pins output the supply voltage (AV _{DD}) for the T6K47. They are electrically connected via an aluminum wire inside the IC chip. Normally a capacitor with a capacitance of approximately 10 μ F is connected across the V _{SS} pins in order to maintain the voltage level.															
V _S IN	I	DC-DC converter 1 power supply input pin This is the power supply feedback pin for DC-DC converter 1. It is normally connected to the V _S OUT1 pin.															
V _{REF} IN	I	Reference voltage input pin An operational-amplifier output feedback voltage is input on this pin to generate the V _S voltage. It should normally be connected to the V _{REF} pin.															
V _{REF}	O	Reference power supply output pin This is an operational-amplifier output pin which generates the V _S voltage. It is normally connected to a capacitor with a capacitance of 0.1 μ F to 0.47 μ F. The capacitance should be adjusted as necessary to suit the conditions in which the device is used.															

Pin Function Description (2)

Pin Name	I/O	Function									
CB1+, CB1- CB2+, CB2- CB3+, CB3- CB4+, CB4- CB5+, CB5-	I/O	DC-DC converter 2 capacitor connection pins Connect these pins to external voltage booster capacitors in order to generate negative voltages for the T6K48. The recommended capacitance for the capacitors is 1 μ F.									
V _{TOUT}	O	DC-DC converter 2 output pin This pin outputs the supply high-level voltage (+13 V) used for the T6K48.									
V _{TIN}	I	DC-DC converter 3 supply voltage input pin The voltage for DC-DC converter 3 used to generate a voltage on the V _{BOUT} pin is input on this pin. It must be connected to the V _{TOUT} pin.									
CC1+, CC1-	I/O	DC-DC converter 3 capacitor connection pins Connect these pins to an external voltage booster capacitor in order to generate negative voltages for the T6K48. The recommended capacitance for the DC-DC converter capacitor is 1 μ F.									
V _{BOUT}	O	DC-DC converter 3 output pin This pin outputs the supply low-level voltage (-13 V) used for the T6K48.									
/STB	I	Standby signal input pin The chip stays in standby state while /STB = L. Enabling the /STB pin halts all the built-in circuits.									
/RST	I	Reset signal input pin A reset signal must be input on this pin after the power is turned on.									
POL	I	Alternating signal input pin This POL signal inverts the phase of the COMOUT, VLC and /VLC signals. See Fig. 2 for an explanation of how to invert the phase.									
VLC /VLC	—	γ -correction power supply voltage pin This pin outputs a voltage whose phase is under the control of the POL signal. The following table lists the output voltages and their phases. <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>POL</th> <th>VLC</th> <th>BVLC</th> </tr> </thead> <tbody> <tr> <td>H</td> <td>VSO</td> <td>0 V</td> </tr> <tr> <td>L</td> <td>0 V</td> <td>VSO</td> </tr> </tbody> </table>	POL	VLC	BVLC	H	VSO	0 V	L	0 V	VSO
POL	VLC	BVLC									
H	VSO	0 V									
L	0 V	VSO									
COMOUT	O	Common signal output pin This pin outputs, in phase with the POL signal, a signal whose level has been converted to the board level necessary for the LCD.									
EXP	I	DC-DC converter ON/OFF switching pin This pin is used to turn the DC-DC converters ON/OFF. Normally it should be connected to GND.									

Pin Function Description (3)

Pin Name	I/O	Function
V _{BAT}	—	Analog circuit supply voltage
V _{DD}	—	Logic circuit supply voltage
V _{CC}	—	DC-DC converter 2 supply voltage
V _{EE}	—	DC-DC converter 3 supply voltage
GND1、GND2	—	Ground pins Note 2: The GND1 and GND2 pins serve different circuit blocks. Connect both pins to ground.

Pin Function Description (4)

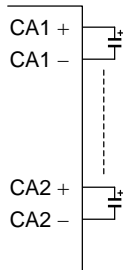
Pin Name	I/O	Function
TEST	I	Test mode switching pin This is an enable pin for Toshiba Test Mode. Normally it should be grounded.
SCK	I	Test mode clock pin A clock pulse for serial data transfer used in Toshiba Test Mode is input on this pin. Normally it should be grounded.
SDA	I	Test mode data pin Serial data used in Toshiba Test Mode is input on this pin. Normally it should be grounded.
FUSE**	I	Toshiba test pin (1) This pin is a dedicated pin used only in Toshiba Test Mode. Normally it should be left open.
FUSE*G	I	Toshiba test pin (2) This pin is a dedicated pin used only in Toshiba Test Mode. Normally it should be left open.
TEG**	I	Toshiba test pin (3) This pin is a dedicated pin used only in Toshiba Test Mode. Normally it should be left open.

Description of Functions and Operation

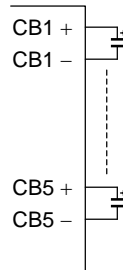
DC-DC converter

The JBT6K49-AS generates an analog supply voltage for the source driver (T6K47) and an LCD-driving voltage for the gate driver (T6K48). The DC-DC converter consists of three circuit blocks which output +4.8 V, +13.0 V and -13.0 V. The ways in which the DC-DC converter can be used are shown below.

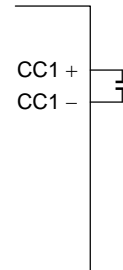
DC-DC converter (1):
Generates +4.8 V.



DC-DC converter (1):
Generates +13.0 V.



DC-DC converter (1):
Generates -13.0 V.



Note 2: Connect a voltage boosting kick capacitor or capacitors to each circuit block. Normally the capacitance of the kick capacitor should be 1.0 μ F. Connect a 10 μ F capacitor across the boosted-voltage output pin and the VSS pin of DC-DC converter (1), since the voltage generated in the DC-DC converter is unstable. In addition, connect a 1 μ F capacitor across the boosted-voltage output pin and the VSS pin of DC-DC converter (1).

Oscillation Circuit

The JBT6K49-AS generates the clock pulse used by the DC-DC converter. The FSEL1 and FSEL2 pins can be used to select the clock oscillation frequency. The following table lists the correspondence between the pin settings and the selected frequency.

FSEL2	FSEL1	Oscillation Frequency (initial value)
0	0	3.5 kHz
0	1	5.0 kHz
1	0	7.0 kHz
1	1	10.0 kHz

Note 3: The relationship of the oscillation frequency and the oscillation resistance depends on assembly and measuring conditions. Therefore, select the oscillation resistance after enough evaluating.

γ -Correction Reference Voltage

The +4.8 V generated by DC-DC converter (1) is used to generate γ -correction reference voltages used by the source driver (T6K47). The voltages generated serve as the maximum and minimum γ -correction voltages. These two voltage levels are switched by the signal input on the POL pin, allowing the γ -correction voltage circuit to be configured easily. Fig.1 is an example of a γ -correction voltage circuit.

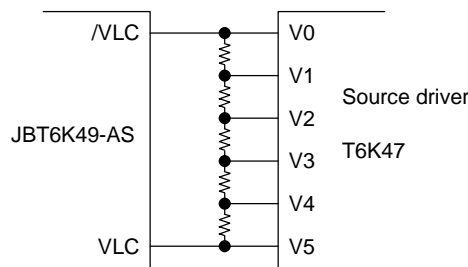


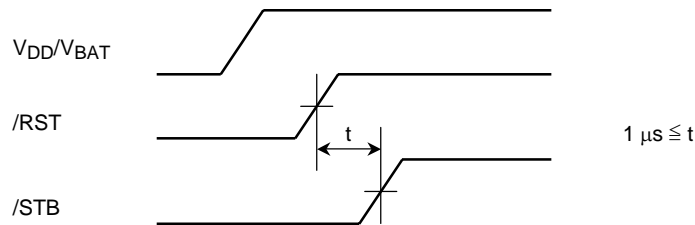
Fig.1 Example of a γ -correction voltage circuit

The following table lists the voltages output from the VLC and /VLC pins and the corresponding levels on the POL pin.

POL	VLC	/VLC	COMOUT
0	0	VSO	0
1	VSO	0	VSO

Power-on

The JBT6K49-AS incorporates a trimming circuit designed to increase the precision of the LCD-driving output voltage. After the power is turned on, the trimming circuit is reset on the leading edge of the signal input on the reset pin. Use the following /RST pin processing sequence after power-on.



Absolute Maximum Ratings (unless otherwise specified, $V_{SS} = 0\text{ V}$ and $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Supply Voltage (1)	V_{DD}	-0.3 to 6.0	V
Supply Voltage (2) (Note 5)	V_{BAT}	-0.3 to 6.5	V
Supply Voltage (3) (Note 5)	V_{CC}	-0.3 to 20	V
Supply Voltage (4)	V_{EE}	-20 to 0.3	V
Input Voltage	V_{IN}	-0.3 to $V_{DD} + 0.3$	V
Output Voltage	V_{OUT}	0 to 6.0	V
Operating Temperature	T_{opr}	-20 to 75	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to 125	$^\circ\text{C}$

Note 4: The voltages listed in the table are referenced to ground (0 V).

Note 5: $V_{BAT} \leq V_{CC}$

Electrical Characteristics

DC Characteristics (1)

(unless otherwise specified, $V_{DD} = 2.7\text{ V}$ to 3.3 V , $V_{BAT} = 2.7\text{ V}$ to 4.2 V and $T_a = -20^\circ\text{C}$ to 75°C)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit	Related Pins
Operating Supply Voltage (1)	V_{DD}	—	—	2.7	—	3.3	V	V_{DD}
Operating Supply Voltage (2)	V_{BAT}	—	—	2.7	—	4.2	V	V_{BAT}
Input Voltage	V_{IL}	—	—	0	—	$0.2 V_{DD}$	V	CKSEL, POL, /STB, EXTCK, FSEL1/2, /RST
	V_{IH}	—	—	$0.8 V_{DD}$	—	V_{DD}		
Input Leakage Current	I_{IL}	—	$V_{inp} = V_{DD}$ to GND	-1.0	—	1.0	μA	CKSEL, POL, /STB, EXTCK, FSEL1/2, /RST
External Clock Frequency	f_{ex}	—	CKSEL = "H"	2	—	8	kHz	EXTCK
External Clock Pulse Duty Ratio	f_{duty}	—		45	50	55	%	EXTCK
External Clock Pulse Rise/Fall Time	t_r/t_f	—		—	—	50	ns	EXTCK

DC Characteristics (2)

(unless otherwise specified, $V_{DD} = 2.7\text{ V}$ to 3.3 V , $V_{BAT} = 2.7\text{ V}$ to 4.2 V and $T_a = -20^\circ\text{C}$ to 75°C ,
For typical ratings the conditions are: $V_{DD} = 3.0\text{V}$, $V_{BAT} = 3.0\text{V}$ and $T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit	Related Pins
Static Drain	I_{DDSTB}	—	/STB = "L"	—	1	5	μA	GND
Dynamic Drain (1)	I_{DD1}	—	With no load	—	0.2	2	μA	V_{DD}
Dynamic Drain (2)	I_{DD2}	—	With typical load $F_{osc} = 3.5\text{ kHz}$	—	0.2	2	μA	V_{DD}
Dynamic Drain (3)	I_{BAT}	—		—	350	500	μA	V_{BAT}

DC Characteristics (3)

(unless otherwise specified, $V_{DD} = 2.7\text{ V to }3.3\text{ V}$, $V_{BAT} = 2.7\text{ V to }4.2\text{ V}$ and $T_a = -20^\circ\text{C to }75^\circ\text{C}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit	Related Pins
DC-DC Converter Characteristic (1)	V_{SO1}	—	$I_{load} = 42\ \mu\text{A}$ $T_a = 25^\circ\text{C}$	4.75	4.80	4.85	V	VSOUT
	V_{SO2}	—	$I_{load} = 42\ \mu\text{A}$ $T_a = -20^\circ\text{C}$ $T_a = 75^\circ\text{C}$	4.75	4.80	4.90		
	V_{SO3}	—	$I_{load} = 2.5\text{mA}$	4.70	—	—		
DC-DC Converter Characteristic (2)	V_{TO1}	—	$I_{load} = 0\ \mu\text{A}$	—	13.0	13.7	V	VTOUT
	V_{TO2}	—	$I_{load} = 100\ \mu\text{A}$	12.3	—	—		
DC-DC Converter Characteristic (3)	V_{BO1}	—	$I_{load} = 0\ \mu\text{A}$	-13.7	-13.0	—	V	VBOOUT
	V_{BO2}	—	$I_{load} = 100\ \mu\text{A}$	—	—	-12.3		

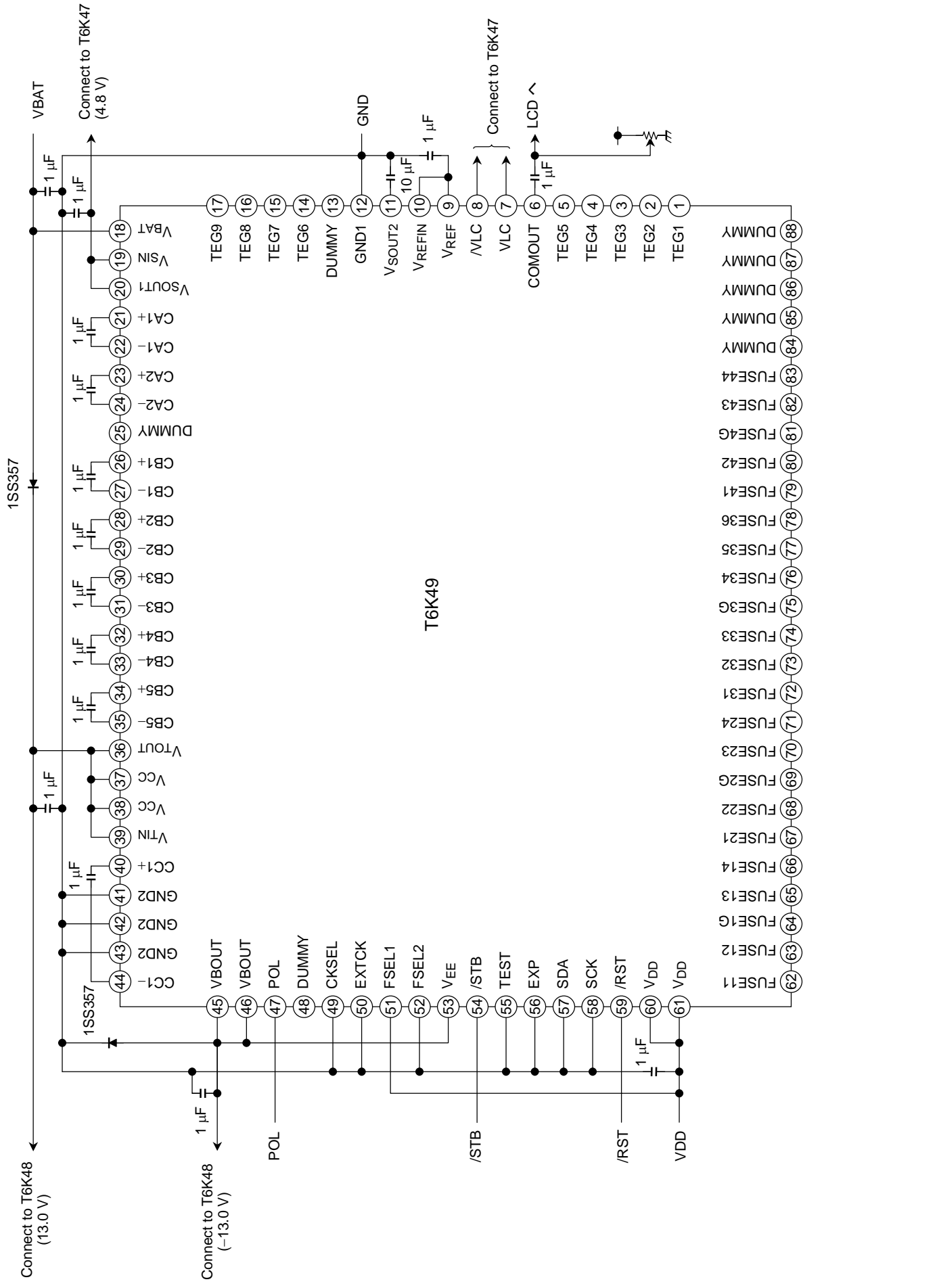
DC Characteristics (4)

(unless otherwise specified, $V_{DD} = 2.7\text{ V to }3.3\text{ V}$, $V_{BAT} = 2.7\text{ V to }4.2\text{ V}$ and $T_a = -20^\circ\text{C to }75^\circ\text{C}$)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit	Related Pins
γ -Output Voltage Characteristic (1)	V_{LC1H}	—	POL = "H"	$V_{SO1} - 0.05$	V_{SO1}	$V_{SO1} + 0.05$	V	VLC
	V_{LC2H}	—		-0.05	0	0.05	V	/VLC
γ -Output Voltage Characteristic (2)	V_{LC1L}	—	POL = "L"	-0.05	0	0.05	V	VLC
	V_{LC2L}	—		$V_{SO1} - 0.05$	V_{SO1}	$V_{SO1} + 0.05$	V	/VLC
COM Output Voltage Characteristic	V_{comL}	—	POL = "L"	-0.05	0	0.05	V	COMOUT
	V_{comH}	—	POL = "H"	$V_{SO1} - 0.05$	V_{SO1}	$V_{SO1} + 0.05$	V	

Application circuit

Internal CR oscillator used (5 kHz)
Using DC-DC converter



RESTRICTIONS ON PRODUCT USE

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- Light striking a semiconductor device generates electromotive force due to photoelectric effects. In some cases this can cause the device to malfunction.
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